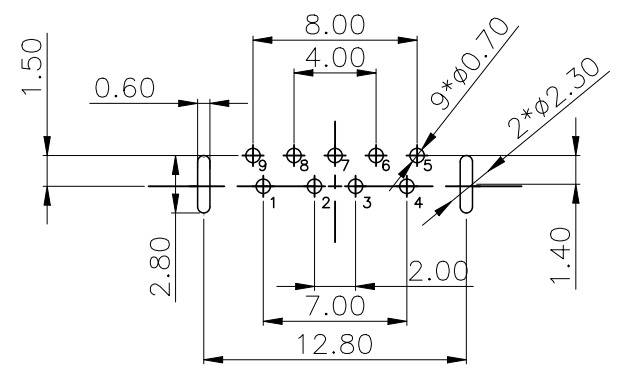
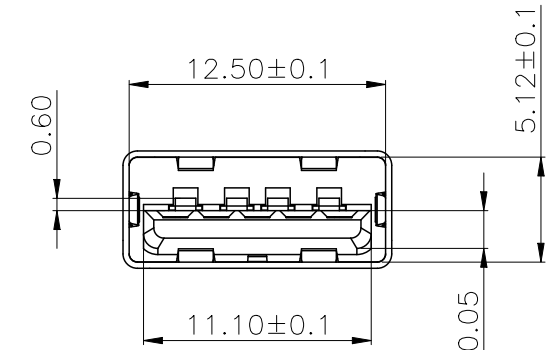
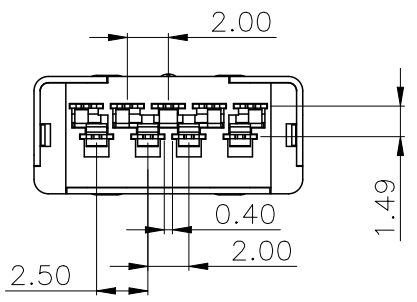
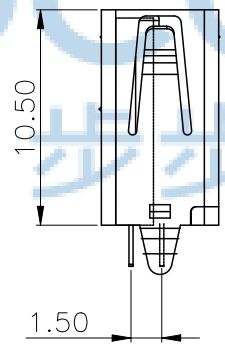
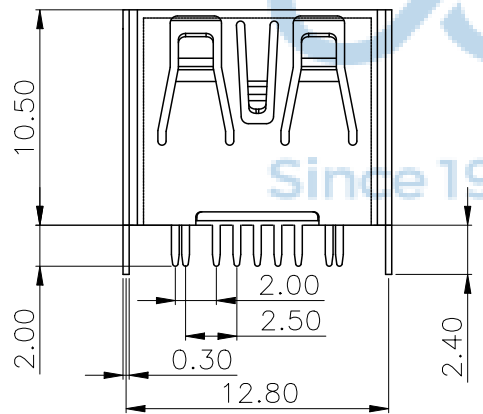


REV	ECN NO	CONTENT	DATE	ENGINEER
A0		INITIAL RELEASE	/	SGF



P. C. B LAYOUT
TOL: ±0.05

- NOTE:
- MATERIAL:
 - INSULATOR:LCP
 - CONTACT:COPPER ALLOY
 - SHELL:SUS201
 - ELECTRICAL CHARACTERISTICS;
 - CONTACT RESISTANCE:30mΩ MAXIMUM
 - CONTACT CURRENT RATING:1.5A
 - DIELECTRIC WITHSTANDING VOLTAGE:100 V R. M. S.
 - INSULATION RESISTANCE 100 MEGOHMS MIN
 - OPERATING TEMPERATURE:-20° C ~ 60° C
 - PLATING
 - TERMINAL:
 - 50u" MIN NICKEL ALL OVER
 - 100u"MIN Tin ON SOLDER AREA
 - (1~30)u"Au ON CONTACT AREA
 - SHELL:50u"MIN. NICEL ALL OVER



Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	Std_A_SSRX-
6	Std_A_SSRX+
7	GND_DRAIN
8	Std_A_SSTX-
9	Std_A_SSTX+
Shell	Shield

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PDWG NO: 0471-1

深圳市步步精科技有限公司

NAME: USB 3.0 AF 180度 H=10.50 两脚直插 端子 DIP 平口 LCP蓝胶 不锈钢外壳 盒装

PJ NO: 127-275-090004-Y4G

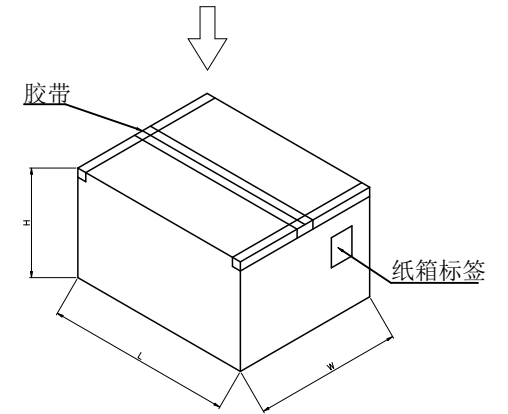
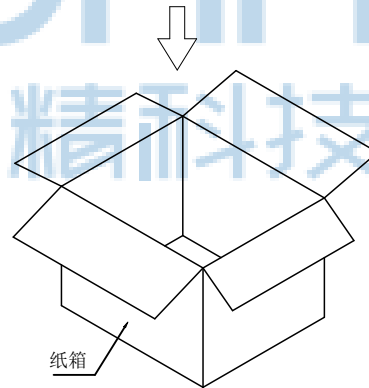
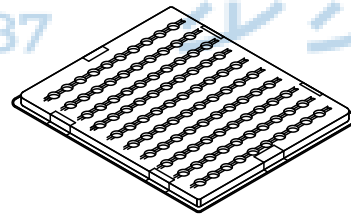
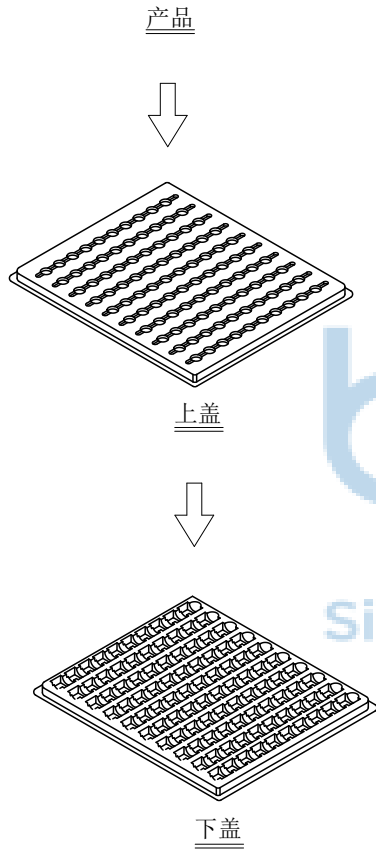
SIZE:A4 DRW NO:

FINISH:SEE NOTES MAT'L:SEE NOTES

SCALE:N/A REV:A0 UNIT:mm PAGE:1/2

APPD	JM_Zheng
CHKD	LYX
DR	SGF

REV	ECN NO	CONTENT	DATE	ENGINEER
A0		INITIAL RELEASE	/	SGF



纸箱规格: L350*W210*H290

1、包装要求:

- 1.1 每盒吸塑盒包装100pcs;
- 1.2 每20盘放一箱, 共计2000PCS;
- 1.3 纸箱外贴上标签。



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PDWG NO: 0471-1		.X: ±0.38 .XX: ±0.25 .XXX: ±0.13	X': ±3" .X': ±2" .XX': ±1"
APPD	JM_Zheng	NAME: USB 3.0 AF 180度 H=10.50 两脚直插 端子 DIP 平口 LCP蓝胶 不锈钢外壳 盒装	
CHKD	LYX	PJ NO: 127-275-090004-Y4G SIZE:A4 DRW NO:	FINISH:SEE NOTES MAT'L:SEE NOTES
DR	SGF	SCALE:N/A REV:A0	UNIT:mm PAGE:2/2